

WDS 850 PCB Soldering Machine Automatic For Motherboard Chip Repairing

Basic Information

- Place of Origin:
- Brand Name:
- Certification:
- Model Number:
- Minimum Order Quantity: 1 UNIT
- Packaging Details: Wooden case
- Delivery Time: 8-15 working days

China WDS

CE

WDS-850

T/T, Western Union, MoneyGram

150 UNITS PER MONTH

- Payment Terms:
- Supply Ability:

Product Specification

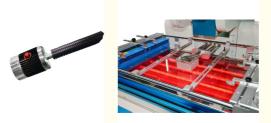
Warranty:	1 Year
Weight:	200KG
Voltage:	AC 220V
Current:	50/60hz
Dimensions:	L970*W7000*H830mm
 Total Power: 	8400W
PCB Size:	Max680*550mm Min 10*10 Mm
BGA Chip Size:	Max120*120mm Min 0.8*0.8mm
• Power:	Ac220v ±10%,50/60hz
• Heater Power:	Upper Temp.one 1600w,second Temp.zone1600w,IR Temp.zone 5000w
 Alignment System: 	Optical Prism + HD Camera
 Highlight: 	WDS 850 PCB Soldering Machine,



WDS 850 PCB Soldering Machine, Automatic PCB Soldering Machine, Automatic BGA Optical Alignment System

More Images





Product Description

HD display Vacuum adsorption WDS-850 Optical alignment automatic repair equipment

Excellent performance features

Multi-language menu interface

Automatic feeding decive

X/Y axis can be controlled by rocker, fast oeration

Imported high-definition CCD(2 million pixels) optical alignment ststem

High precision temperature control system, accurate temperature control system, accurate temperature control



Power	AC 220V±10 50Hz	Total power	7600W
Up heater power	Max 1200W	Mount max load	800G
Down heater power	Max1200W	IR power	5000W (2000 ^{Wntrolled})
Max PCB size	630*480mm	Min PCB size	10×10mm
Chip magnification	2-50 multiple	Temp. interface	5个
Suit PCB thickness	0.5-8mm	Mount accuracy	±0.01mm
Suit chip size	0.8*0.8~80*80mm	Chip min spacing	0.15mm
Dimensions	L970*W700*H830mm	Weight	About 210KG

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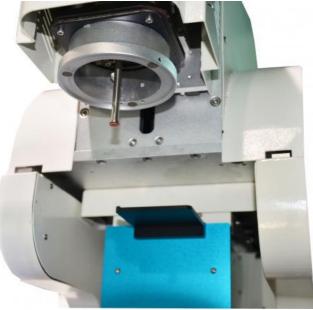
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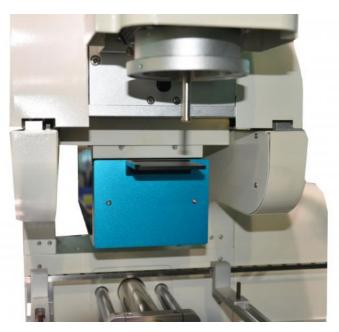
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HD optical alignment and intelligent control

The integrated design of hot air head and mounting head has the functions of automatic mounting, automatic welding and automatic disassembly. High precision K-type thermocouple (KSENSOR) cLOSED Loop control, up and down independent temperature measurement, temperature control accuracy up to ± 1 degree, Over-temperature protection alarm function, software encryption and anti-stay function.



HD display

High-definition imported CCD(2 million pixels) digital imaging, automatic optical zoom system, automatic precision alignment control system with laser red dot, using 15 inch high-definition industrial display screen dispaly.



Vacuum adsorption and preheating platform

The upper heating head is equipped with a vacuum suction pipe for chip adsorption. The bottom preheating platform adopts imported excellent heating materials(infrared gold-plated light tube)+anti-flash thermostatic glass (temperature resistance up to 1800°C). The preheating area is up to 500*420mm. The preheating platform, splint device and cooling system can be moved as a whole in the X direction. Make PCB positioning and folding welding more safe and convenient.



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Specification

Model	WDS-850
Total power supply	8400W
Upper heating power supply	1600W
Lower heating power supply	1600W
IR heating power supply	5000W(2000W controlled)
Power supply	220V, 50/60Hz
Maximum	680*550mm
Minimum	10*10mm
Temperature measuring interfaces	5pcs

Chip zoom in and zoom out	2-50/times
The PCB thickness	0.5 8mm
Apply chip size	0.8*0.8 120*120mm
Applicable minimum chip spacing	0.15mm
Maximum mouting load	300g
Mounting precision	±0.01mm
Machine dimension	L970*W700*H830mm
Machine weight	200KG

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